

Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	12 X 12 X 0.85 (6.0 EP)
LeadCount	88
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A Compliant
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.60E-01	86.9	869100	44.19	441895
Thermosets	Epoxy & Phenol Resin	Proprietary	2.35E-02	12.8	127800	6.50	64980
Other inorganic materials	Carbon black	1333-86-4	5.71E-04	0.3	3100	0.16	1576
Subtotal			1.84 E-01	100.00	1000000	50.85	508451

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.52 E-01	96.40	963989	41.93	419302
Copper & its alloys	Nickel	7440-02-0	3.94 E-03	2.50	25006	1.09	10877
Copper & its alloys	Silicon	7440-21-3	9.46 E-04	0.60	6004	0.26	2611
Copper & its alloys	Zinc	7440-66-6	7.88 E-04	0.50	5001	0.22	2175
Subtotal			1.58 E-01	100.00	1000000	43.50	434965

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.92 E-04	100.0	1000000	0.27	2739

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.11 E-03	100.0	1000000	1.13	11335

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.28 E-03	100.0	1000000	1.46	14572

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.41 E-03	100.0	1000000	2.60	25985

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.09 E-04	73.40	734000	0.03	300
Thermoset	Epoxy Resin	Proprietary	2.72 E-05	18.35	183500	0.01	75
Other inorganic materials	Metal oxide	Proprietary	4.07 E-06	2.75	27500	0.00	11
Others	Curing and hardening agent	Proprietary	4.07 E-06	2.75	27500	0.00	11
Other organic materials	Gamma Butyrolactone	96-48-0	4.07 E-06	2.75	27500	0.00	11
Subtotal			1.48 E-04	100.0	1000000	0.04	409

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy Resin	Proprietary	3.69 E-04	66.00	90648649	0.10	1019
Others	Polymeric Resin	Proprietary	1.90 E-04	34.00	46697789	0.05	525
Subtotal			5.59 E-04	100.0	137346437	0.15	1544

Package Totals	Weight (g)	Percentage (%)	PPM
	3.62 E-01	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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